



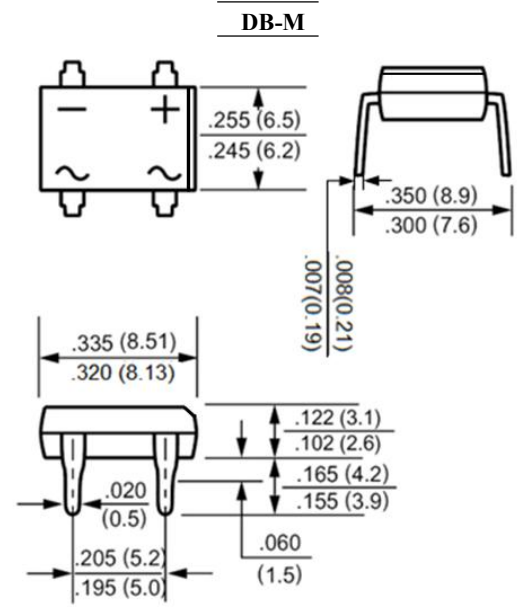
# DB101 THRU DB107

## FEATURES

- Glass passivated chip junction
- Low forward voltage drop
- High surge current capability
- Ideal for printed circuit board
- High temperature soldering guaranteed:  
260°C for 10 seconds

## MECHANICAL DATA

Case: Molded plastic, DB-M  
 Epoxy: UL 94V-0 rate flame retardant  
 Terminals: Pure tin plated, lead free, Leads solderable per MIL-STD-202, method 208 guaranteed  
 Mounting position: as Marking  
 Weight: 0.34gram



## Maximum Ratings and Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified.  
 Single phase, half wave, 60HZ, resistive or inductive load.  
 For capacitive load, derate current by 20%.

	Symbols	DB101	DB102	DB103	DB104	DB105	DB106	DB107	Units
Maximum Recurrent Peak Reverse Voltage	$V_{RRM}$	50	100	200	400	600	800	1000	Volts
Maximum RMS Voltage	$V_{RMS}$	35	70	140	280	420	560	700	Volts
Maximum DC Blocking Voltage	$V_{DC}$	50	100	200	400	600	800	1000	Volts
Maximum Average Forward Rectified Current at $T_A=40^\circ\text{C}$	$I_{(AV)}$	1.0							Amp
Peak Forward Surge Current, 8.3ms single half-sine-wave superimposed on rated load (JEDEC method)	$I_{FSM}$	30							Amp
Maximum Forward Voltage at 1.0A DC and 25°C	$V_F$	1.10							Volts
Maximum Reverse Current at $T_A=25^\circ\text{C}$ at Rated DC Blocking Voltage $T_A=125^\circ\text{C}$	$I_R$	5.0 500							uAmp
Operating and Storage Temperature Range	$T_J, T_{stg}$	-55 to +150							°C



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FIG.1 FORWARD CURRENT DERATING CURVE

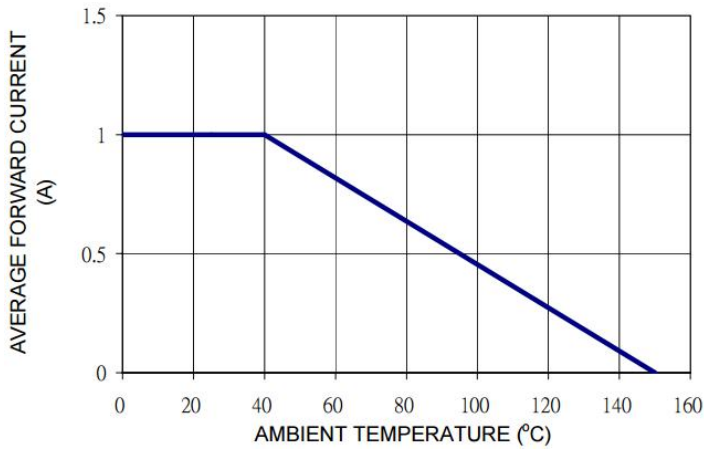


FIG. 2 TYPICAL REVERSE CHARACTERISTICS

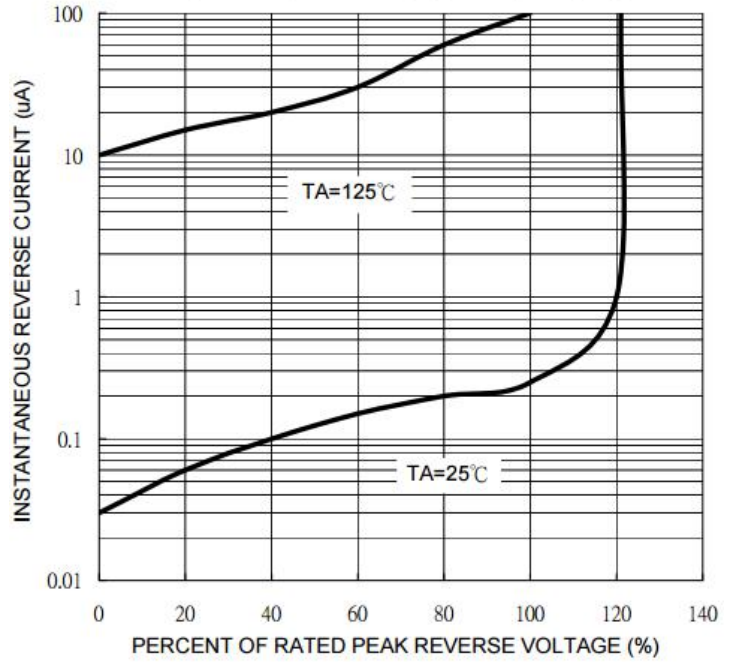


FIG. 3 MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

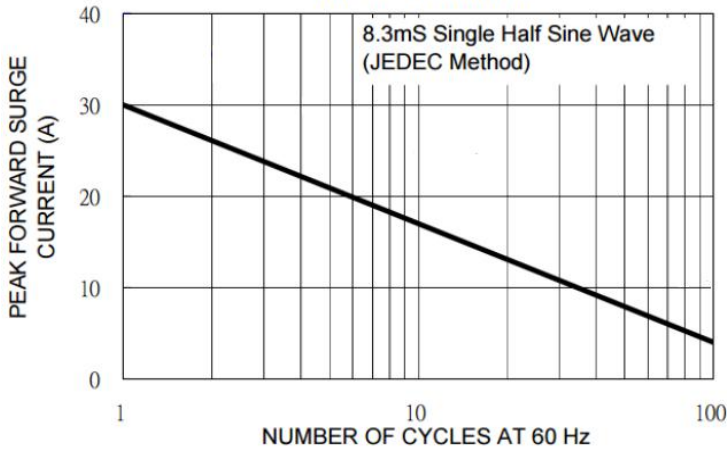


FIG. 5 TYPICAL FORWARD CHARACTERISTICS

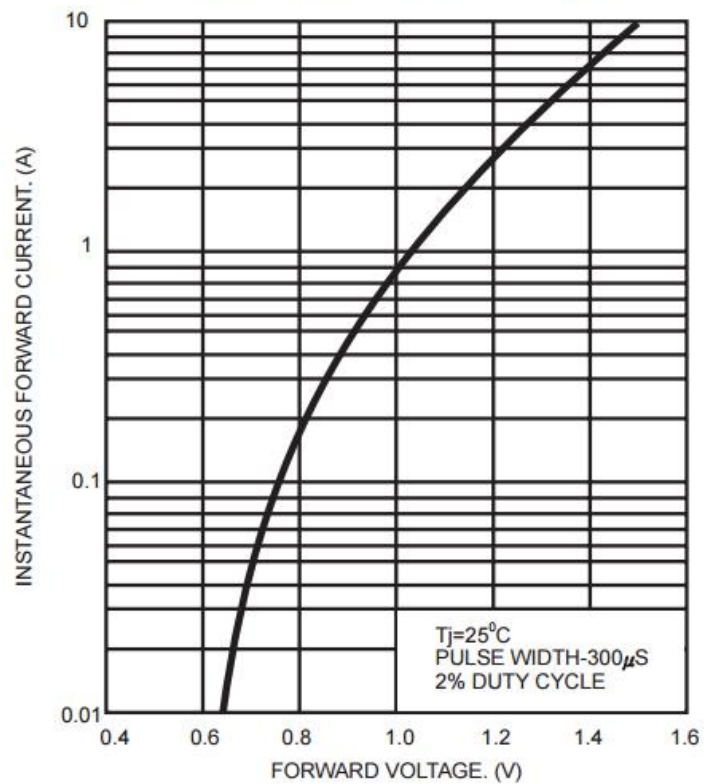
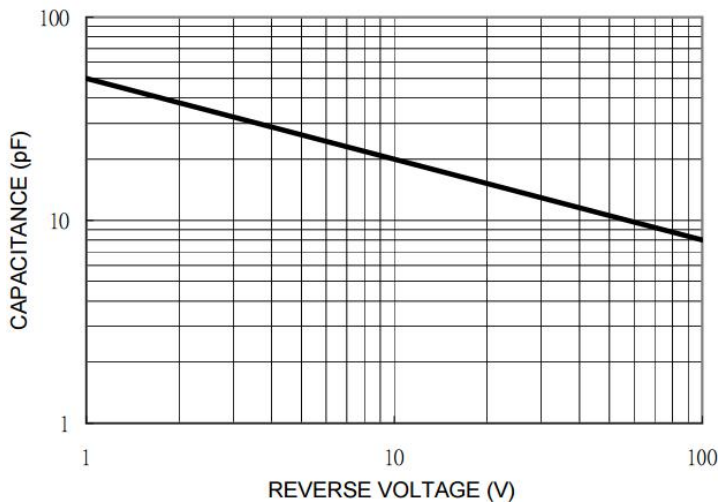


FIG. 4 TYPICAL JUNCTION CAPACITANCE



单击下面可查看定价，库存，交付和生命周期等信息

[>>ZG\(中鑫半导体\)](#)